

WHAT IS CLAIMED IS:

Sub 2 → 1. A semiconductor storage device constituted in such a way that it causes a lower chip and an upper chip are superimposed on a substrate comprising:

5 a wiring substrate for relaying electric connection between said upper chip and said substrate which wiring substrate is provided between said lower chip and said upper chip.

2. A semiconductor storage device as claimed in claim 1, wherein there are provided a first terminal connected to a terminal on a surface of said upper chip, a second terminal connected to a terminal on a surface of said substrate, and a wiring pattern for connecting said first and said 5 second terminals on the surface of said wiring substrate.

3. A semiconductor storage device as claimed in claim 2, further comprising:

a first bonding wire for connecting said terminal of the surface of said upper chip with said first terminal; and

5 a second bonding wire for connecting said terminal of the surface of said substrate with said second terminal.

4. A semiconductor storage device as claimed in claim 1, wherein there is provided a wiring pattern whose one end is connected to a terminal on a rear surface of said upper chip, and whose other terminal is connected to a terminal on a surface of said lower chip.

5. A semiconductor storage device as claimed in claim 2, wherein said terminal of the surface of said lower chip is connected to said terminal of the surface of said substrate by a third bonding wire.

6. A semiconductor storage device as claimed in claim 4, wherein said terminal of the surface of said lower chip is connected to said terminal of the surface of said substrate by a third bonding wire.

7. A semiconductor storage device as claimed in claim 1, wherein said wiring substrate is sheet shape wiring substrate.

8. A semiconductor storage device as claimed in claim 1, wherein said wiring substrate is board shape wiring substrate.